

In the Claims:

Claims 1 to 11 (canceled).

12. (new) A method for producing a circuit arrangement having a carrier body with circuit components secured to an upper side (12) of said carrier body having thermal lead-through vias (7) passing through said carrier body (5) from said upper side (12) to an underside (13) of said carrier body, said method comprising the following steps:
- a) first applying a first metallization base layer (6) to said carrier body (5) and to said thermal lead-through vias (7),
  - b) screen printing a viscous material (8) into said thermal lead-through vias (7) thereby closing said thermal lead-through vias (7) to prevent solder of a following soldering step from passing through said thermal lead-through vias,
  - c) removing, following curing of said viscous material, any excess of said viscous material (8) from said underside (13) of said carrier body (5), and
  - d) second applying at least one further metallization layer (17) to said first metallization base layer (6) outside said viscous material on the inside of said thermal lead-through vias, on the upper side and on the underside of said carrier body.

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1 13. (new) The method of claim 12, wherein said second applying  
2 step is performed outside said viscous material (8)  
3 covering a portion of said first metallization base layer  
4 in said lead-through vias (7).

1 14. (new) The method of claim 12, wherein said removing step is  
2 performed as a mechanical cleaning process.

1 15. (new) The method of claim 14, wherein said mechanical  
2 cleaning process is performed as a mechanical brush  
3 grinding step.

1 16. (new) The method of claim 12, wherein said removing step is  
2 performed as a chemical cleaning process.

1 17. (new) The method of claim 12, further comprising, following  
2 said second applying step, a step of attaching said circuit  
3 components (1) to said upper side (12) by a reflow  
4 soldering process.

1 18. (new) The method of claim 12, further comprising, following  
2 said second applying step, a step of applying a thermally  
3 conducting, electrically insulating film (9) to said  
4 underside (13) of said carrier body.

1 19. (new) The method of claim 18, further comprising connecting  
2 said thermally conducting, electrically insulating film to  
3 a cooling body.

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1     **20.**   (new) The method of claim 12, further comprising using as  
2           said viscous material a solid epoxy material which is  
3           sufficiently viscous for performing said screen printing  
4           step.

1     **21.**   (new) The method of claim 12, further comprising performing  
2           said step of screen printing on said underside (13) of said  
3           carrier body.

1     **22.**   (new) The method of claim 12, wherein said second applying  
2           step is performed by applying a nickel-gold coating to said  
3           first metallization base layer outside said viscous  
4           material, to form said second metallization layer (17).

**[RESPONSE CONTINUES ON NEXT PAGE]**